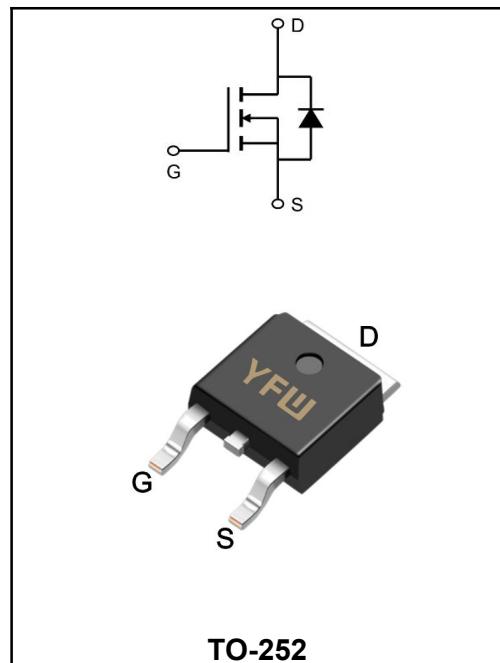


68V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	80A
V_{DSS}	68V
$R_{DS(on)}\text{-typ}(@V_{GS}=10V)$	< 8.6mΩ (Type: 6.5 mΩ)


Applications

- ◆ Battery protection
- ◆ Load switch
- ◆ Uninterruptible power supply

Maximum Ratings at $T_c=25^\circ C$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	68	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=25^\circ C$	I_D	80	A
Continuous Drain Current, $V_{GS} @ 10V^1$ @ $T_c=100^\circ C$	I_D	52	A
Pulsed Drain Current ²	I_{DM}	320	A
Single Pulse Avalanche Energy ³	E_{AS}	121	mJ
Avalanche Current	I_{AS}	22	A
Total Power Dissipation ⁴ @ $T_c=25^\circ C$	P_D	116	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	63	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	0.85	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	BV _{DSS}	68	72	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA	ΔBV _{DSS/ΔTJ}	-	0.023	-	V/°C
Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =10A	R _{DS(ON)}	-	6.5	8.6	mΩ
Gate -Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	V _{GS(th)}	2.0	3.0	4.0	V
V _{GS(th)} Temperature Coefficient		ΔV _{GS(th)}	-	-4.2	-	mV/°C
Drain -Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =25°C	I _{DSS}	-	-	1	μA
	V _{DS} =24V , V _{GS} =0V , T _J =55°C		-	-	5	
Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Forward Transconductance	V _{DS} =5V, I _D =10A	g _{FS}	-	5.5	-	S
Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz	R _g	-	2.3	-	Ω
Total Gate Charge(4.5V)	V _{DS} =30V V _{GS} =10V I _D =20A	Q _g	-	35	-	nC
Gate-Source Charge		Q _{gs}	-	11	-	
Gate-Drain Charge		Q _{gd}	-	9	-	
Turn-on delay time	V _{DS} =30V I _D =20A R _{GEN} =6Ω V _{GS} =10V	t _{d(on)}	-	15	-	ns
Rise Time		T _r	-	94	-	
Turn-Off Delay Time		t _{d(OFF)}	-	46	-	
Fall Time		t _f	-	32	-	
Input Capacitance	V _{DS} =15V V _{GS} =0V f=1MHz	C _{iss}	-	4062	-	pF
Output Capacitance		C _{oss}	-	261	-	
Reverse Transfer Capacitance		C _{rss}	-	231	-	
Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	I _s	-	-	80	A
Pulsed Source Current ^{2,5}		I _{SM}	-	-	320	A
Diode Forward Voltage ²	V _{GS} =0V , I _s =80A	V _{SD}	-	-	1.2	V
Reverse Recovery Time	I _F =20A , dI/dt=100A/μs , T _J =25°C	t _{rr}	-	78	-	ns
Reverse Recovery Charge		Q _{rr}	-	51	-	nC

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The test cond ≤ 300us duty cycle ≤ 2%, duty cycle ition is T_J =25°C, VDD =35V, V G =10V, R G =25Ω, L=0.5mH, IAS =22A
- 4、The power dissipation is limited by 175°C junction temperature
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

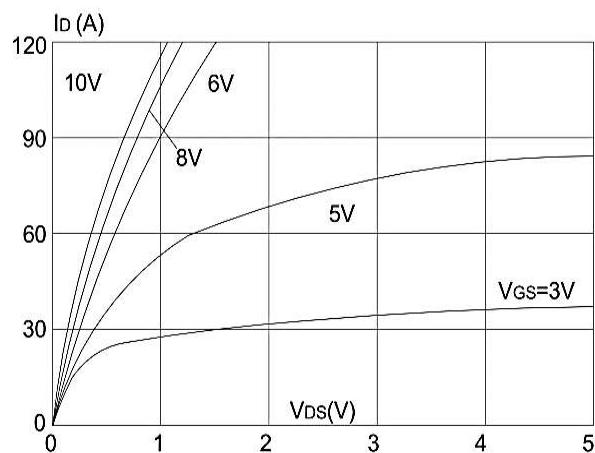


Figure 1: Output Characteristics

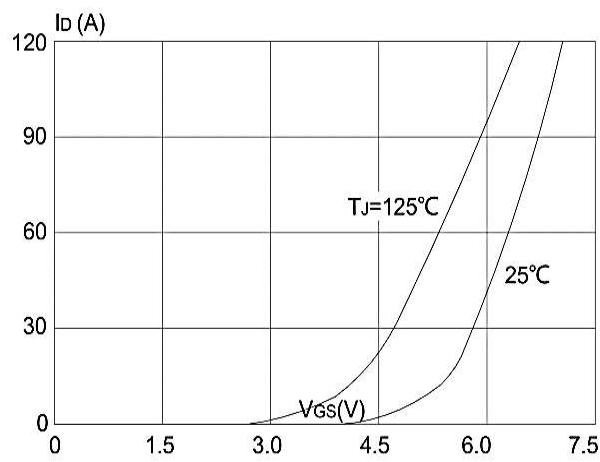


Figure 2: Typical Transfer Characteristics

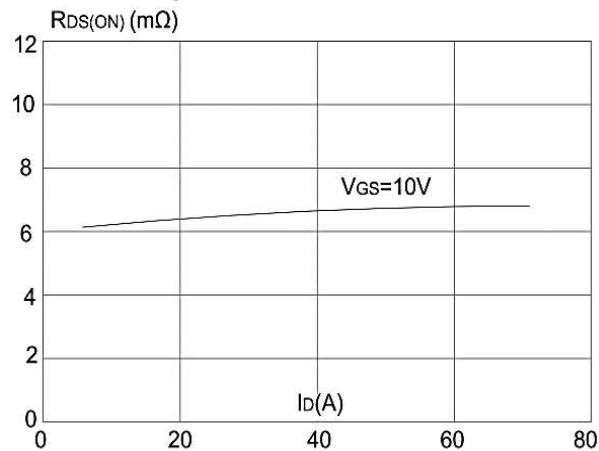


Figure 3: On-resistance vs. Drain Current

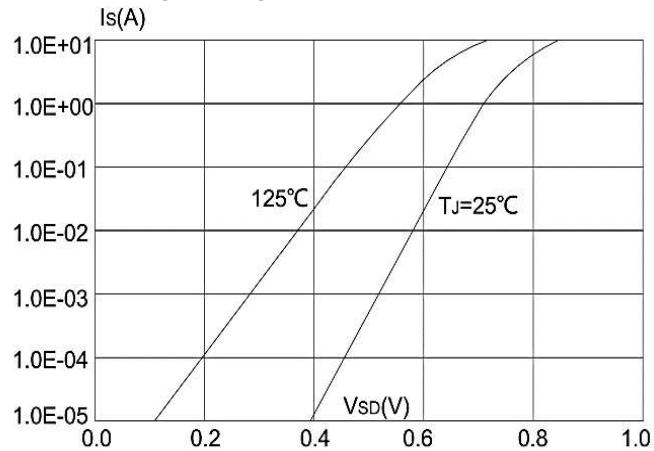


Figure 4: Body Diode Characteristics

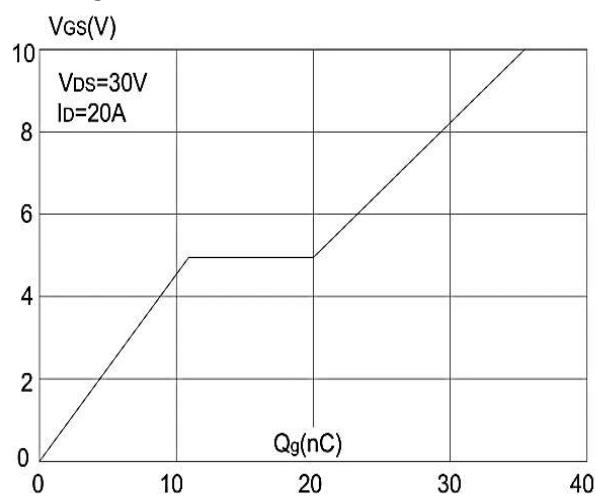


Figure 5: Gate Charge Characteristics

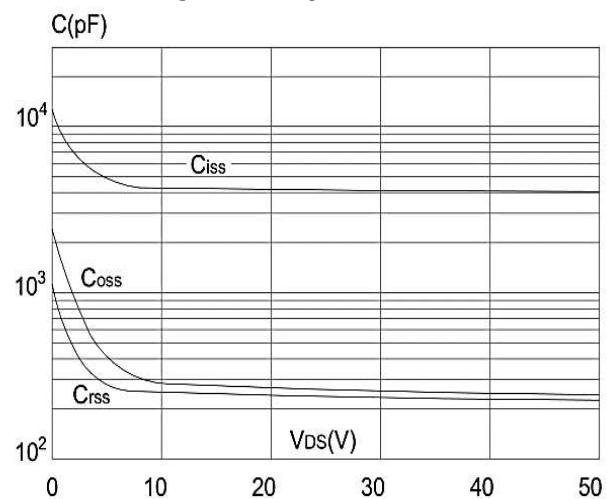


Figure 6: Capacitance Characteristics

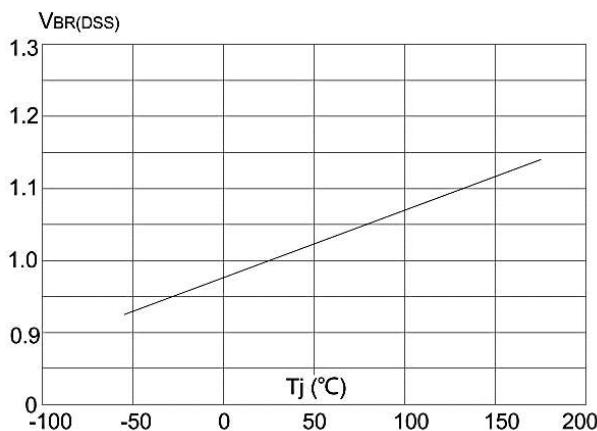
Ratings and Characteristic Curves


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

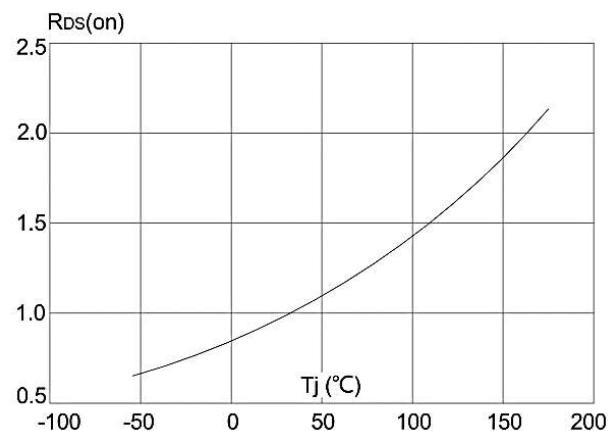


Figure 8: Normalized on Resistance vs. Junction Temperature

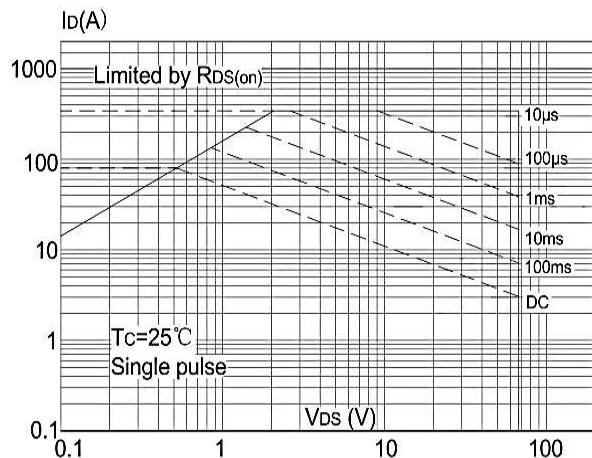


Figure 9: Maximum Safe Operating Area

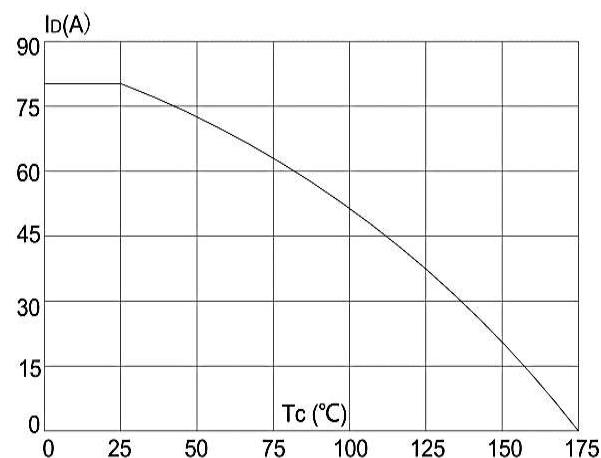


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

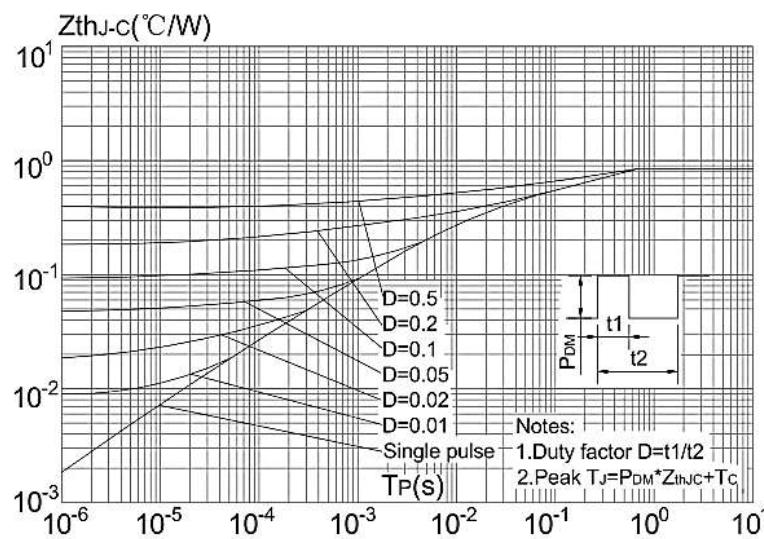
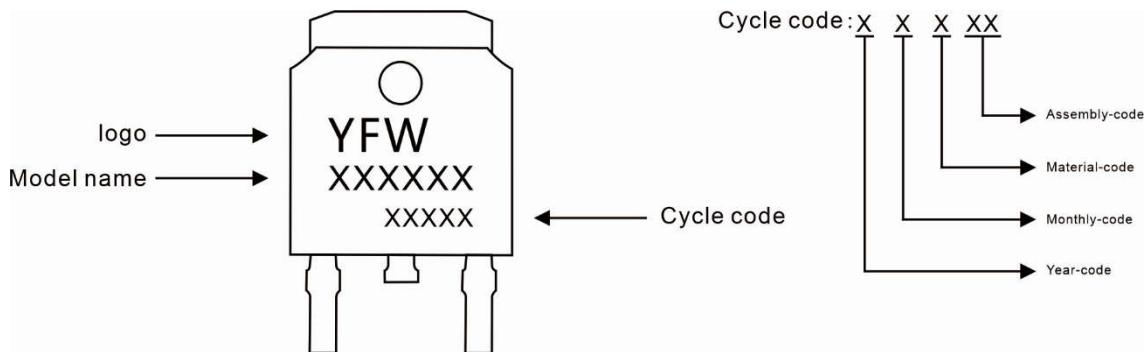


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

Marking Diagram



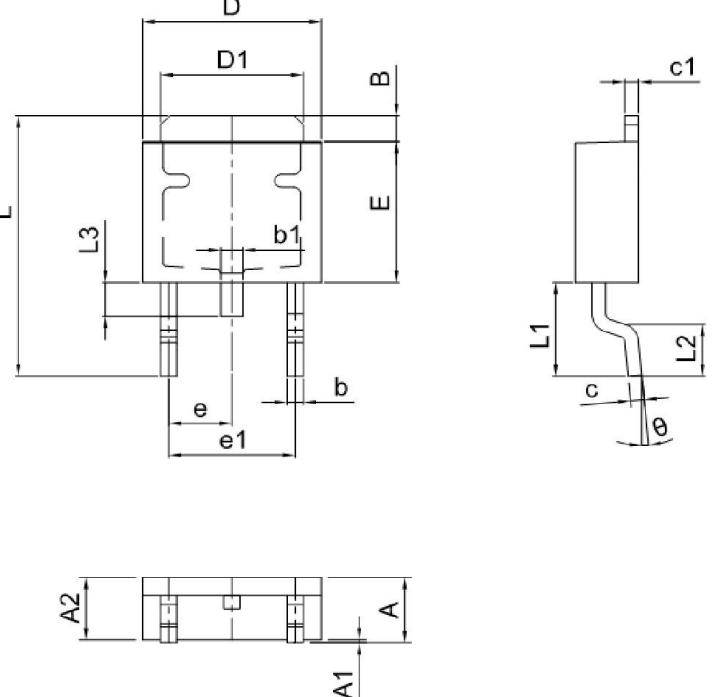
Ordering information

Model name	Package	Unit Weight	Base Quantity	Packing Quantity
YFW80N07AD	TO-252	0.011oz(0.32g)	2500pcs/reel	5000pcs/box 25000pcs/Carton

Package Dimensions

TO-252

Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.50	0.087	0.098
A1	0.00	0.12	0.000	0.005
A2	2.20	2.40	0.087	0.094
B	1.20	1.60	0.047	0.063
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.35	6.65	0.250	0.262
D1	5.20	5.40	0.205	0.213
E	5.40	5.70	0.213	0.224
e	2.20	2.40	0.087	0.094
e1	4.40	4.80	0.173	0.189
L	10.00	11.00	0.393	0.433
L1	2.70	3.10	0.106	0.122
L2	1.40	1.80	0.055	0.071
L3	0.90	1.50	0.035	0.059



Technical drawing of the TO-252 package showing front and side views with dimension labels L, D, E, A, B, etc. The front view shows the overall height L, lead spacing A, and lead width A1. The side view shows the lead thickness c, lead pitch c1, and lead height L1. The top view shows the chip size D, D1, and E, along with lead thickness e and lead height e1.

Disclaimer

The information presented in this document is for reference only. GuangDong Youfeng Microelectronics Co.,Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise. The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices). YFW or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale. This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <https://www.yfwdiode.com>, or consult YFW sales office for further assistance.